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10/609,634	07/01/2003	Kazunari Kimino	R2180.0159/P159	4954

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DICKSTEIN SHAPIRO LLP  
1825 EYE STREET NW  
Washington, DC 20006-5403

EXAMINER
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KOCH, GEORGE R

ART UNIT	PAPER NUMBER
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1734

SHORTENED STATUTORY PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE
3 MONTHS	02/23/2007	PAPER

**Please find below and/or attached an Office communication concerning this application or proceeding.**

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

# Office Action Summary

Application No.

10/609,634

Applicant(s)

KIMINO, KAZUNARI

Examiner

George R. Koch III

Art Unit

1734

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

## Status

- 1) ☒ Responsive to communication(s) filed on 21 November 2006.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

## Disposition of Claims

- 4) ☒ Claim(s) 1-40 is/are pending in the application.
- 4a) Of the above claim(s) 12-22 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-11 and 23-40 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

## Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

## Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
  - ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

## Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_

- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date. \_\_\_\_\_
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: \_\_\_\_\_

## **DETAILED ACTION**

### ***Response to Arguments***

1. Applicant's arguments with respect to claims 1-11 and 23-40 have been considered but are unpersuasive.
2. Applicant argues that the amendments overcome the rejections. This is unpersuasive. Examiner reiterates the point that in response to applicant's argument that the imaging functions are different, a recitation of the intended use of the claimed invention must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim.
3. It should be noted that Bouras, at the very least, discusses the concept of using the CCD camera to view the substrate prior to dispensing, in order to facilitate the positioning of the dispensing needle (see column 6, lines 17-36). It should also be noted that the Bouras reference incorporates by reference the parent application of the Ciardella reference in column 3, lines 62-65 of Bouras.
4. In response to applicant's argument that there is no suggestion to combine the references (Ciardella and Bouras), the examiner recognizes that obviousness can only be established by combining or modifying the teachings of the prior art to produce the claimed invention where there is some teaching, suggestion, or motivation to do so found either in the references themselves or in the knowledge generally available to one

Art Unit: 1734

of ordinary skill in the art. See *In re Fine*, 837 F.2d 1071, 5 USPQ2d 1596 (Fed. Cir. 1988) and *In re Jones*, 958 F.2d 347, 21 USPQ2d 1941 (Fed. Cir. 1992). In this case, Bouras is merely being relied upon for details as to the temperature controller, and to show that it would be obvious that Ciardella can handle the substrates in Bouras.

5. This argument is NOT an admission that Bouras cannot be combined with Ciardella. It is unclear why the two references cannot be combined, as the Bouras reference is clearly a modification of the Ciardella reference, and both involve similar inventors. It should also be noted that the Bouras reference incorporates by reference the parent application of the Ciardella reference in column 3, lines 62-65 of Bouras. Thus, Bouras is intentionally an improvement of Ciardella, and includes all of the teachings of Ciardella.

### ***Claim Rejections - 35 USC § 102***

6. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.

7. Claims 1, 2, 6-8, 10, 11 and 23, 24, 28-30, and 32-33 are rejected under 35 U.S.C. 102(b) as being anticipated by Ciardella (US 5,711,989).

As to claim 1 and 23, Ciardella discloses an apparatus (see Figure 5) for manufacturing a semiconductor device, comprising: a substrate holding unit (conveyor and fixer - see lift and lock mechanism in column 3, lines 5-13 and column 5, lines 36-40) for holding a semiconductor wafer substrate (i.e., a circuit board with semiconductor

Art Unit: 1734

elements thereon, see columns 1-10), wherein said semiconductor wafer substrate is capable of being provided with at least one electrode formed on a first surface thereof (chip 10, solder balls 12, etc), a discharging mechanism (syringe 20 and dispensing needle 22) which is explicitly for discharging droplets (see abstract, which recites "drop generator") of viscous material (for example, column 8, lines 8-10) contained in a viscous material container unit (syringe 84) through at least one discharging nozzle (nozzle 70) onto said first surface of said semiconductor wafer substrate held on said substrate holding unit; a drive mechanism (conveyor 22 and XYZ electromechanical positioner 38) for displacing at least one of said semiconductor wafer substrate and said discharging nozzle; and a control unit (items 18, 38, 40, and 42) for controlling said discharging mechanism and said drive mechanism such that said raw sealant resin is attached to said first surface of said semiconductor wafer substrate except at least a portion of said electrode. The camera and vision circuit is an image information device (item 16 and 44) that provides image information of the substrate (such as the location of the drops), and effectively allows for the positioning of the drive mechanism of the nozzle, and therefore provides and is capable of providing the control unit functionality as claim. The camera is capable of capturing the image prior to discharge. The apparatus of Ciardella, disclosed as dispensing viscous material, is capable of dispensing any sub-species of viscous material including raw sealant resin.

As to claim 2 and 24, Ciardella is capable of being used wherein said electrode formed on said first surface of said semiconductor wafer substrate is a protruded-shaped electrode, and wherein said control unit is adapted to control said discharging

Art Unit: 1734

mechanism and said drive mechanism such that said raw sealant resin is attached to said first surface except a tip portion of said protruded-shaped electrode.

As to claim 6 and 28, Ciardella discloses a heater (see column 6, lines 64-67 and column 7, lines 1-19) for heating said raw sealant resin contained in said resin container unit.

As to claim 7 and 29, the control unit of Ciardella is capable of controlling said discharging mechanism and said drive mechanism such that said raw sealant resin is not attached to at least a portion of dicing lines of said semiconductor wafer substrate.

As to claim 8 and 30, the control unit of Ciardella is capable of being adapted to control said discharging mechanism and said drive mechanism such that said raw sealant resin is not attached to dicing lines of said semiconductor wafer substrate and forms a layer with edges of a rounded shape in a vicinity of intersecting points of said dicing lines.

As to claim 10 and 32, the control unit of Ciardella is capable of controlling said discharging mechanism and said drive mechanism such that said raw sealant resin is not attached to at least a portion of dicing lines of said semiconductor wafer substrate.

As to claim 11 and 33, the control unit of Ciardella is capable of controlling said discharging mechanism and said drive mechanism such that said raw sealant resin is not attached to dicing lines of said semiconductor wafer substrate and forms a layer with edges of a rounded shape in vicinity of intersecting points of said dicing lines.

Art Unit: 1734

8. Claims 1, 2, 4, 6-8, 10, 11 and 23, 24, 26, 28-30, 32-36, 38 and 40 are rejected under 35 U.S.C. 102(b) as being anticipated by Bouras (US 5,906,682), as evidenced by Ciardella '777 (US 5,505,777). It should be noted that the Bouras reference incorporates by reference the US 5,505,777 to Ciardella reference in column 3, lines 62-65 of Bouras.

As to claim 1 and 23, Bouras and Ciardella '777 discloses an apparatus (see Figure 5 of Bouras, Figure 2 of Ciardella '777) for manufacturing a semiconductor device, comprising: a substrate holding unit (conveyor and fixer - see lift and lock mechanism in Ciardella '777, column 3, lines 5-13 and column 5, lines 36-40) for holding a semiconductor wafer substrate (i.e., a circuit board with semiconductor elements thereon, see columns 1-10), wherein said semiconductor wafer substrate is capable of being provided with at least one electrode formed on a first surface thereof (chip 10, solder balls 12, etc), a discharging mechanism (syringe 20 and dispensing needle 22, see also Figure 3 of Ciardella '777) which is explicitly for discharging droplets (see abstract, which recites "drop generator") of viscous material (for example, column 8, lines 8-10) contained in a viscous material container unit (syringe 20 of Bouras, syringe 84 of Ciardella '777) through at least one discharging nozzle (nozzle 70) onto said first surface of said semiconductor wafer substrate held on said substrate holding unit; a drive mechanism (conveyor 22 and XYZ electromechanical positioner 38) for displacing at least one of said semiconductor wafer substrate and said discharging nozzle; and a control unit (items 18, 38, 40, and 42) for controlling said discharging mechanism and said drive mechanism such that said raw sealant resin is attached to

Art Unit: 1734

said first surface of said semiconductor wafer substrate except at least a portion of said electrode. The camera and vision circuit is an image information device (item 16 and 44) that provides image information of the substrate (such as the location of the drops), and effectively allows for the positioning of the drive mechanism of the nozzle, and therefore provides and is capable of providing the control unit functionality as claim. The apparatus of Bouras, disclosed as dispensing viscous material, is capable of dispensing any sub-species of viscous material including raw sealant resin. Bouras explicitly discloses capturing image information of the substrate prior to discharge (see column 6, lines 18-36).

As to claim 2 and 24, Bouras is capable of being used wherein said electrode formed on said first surface of said semiconductor wafer substrate is a protruded-shaped electrode, and wherein said control unit is adapted to control said discharging mechanism and said drive mechanism such that said raw sealant resin is attached to said first surface except a tip portion of said protruded-shaped electrode.

As to claim 4 and 26, Bouras (see column 3, lines 62-65) discloses an improvement of Ciardella '777 wherein the substrate holding unit is provided with a substrate temperature control mechanism (item 44, 46 and 47, see column 5, lines 32-47) for controlling a temperature of at least said semiconductor wafer substrate.

As to claim 6 and 28, both Bouras (item 26) and Ciardella '777 (see column 6, lines 64-67 and column 7, lines 1-19) disclose a heater for heating said raw sealant resin contained in said resin container unit.



As to claim 7 and 29, the control unit of both Bouras and Ciardella '777 is capable of controlling said discharging mechanism and said drive mechanism such that said raw sealant resin is not attached to at least a portion of dicing lines of said semiconductor wafer substrate.

As to claim 8 and 30, the control unit of both Bouras and Ciardella '777 is capable of being adapted to control said discharging mechanism and said drive mechanism such that said raw sealant resin is not attached to dicing lines of said semiconductor wafer substrate and forms a layer with edges of a rounded shape in a vicinity of intersecting points of said dicing lines.

As to claim 10 and 32, the control unit of both Bouras and Ciardella '777 is capable of controlling said discharging mechanism and said drive mechanism such that said raw sealant resin is not attached to at least a portion of dicing lines of said semiconductor wafer substrate.

As to claim 11 and 33, the control unit of both Bouras and Ciardella '777 is capable of controlling said discharging mechanism and said drive mechanism such that said raw sealant resin is not attached to dicing lines of said semiconductor wafer substrate and forms a layer with edges of a rounded shape in vicinity of intersecting points of said dicing lines.

As to claim 34, Bouras, which discloses an improvement of Ciardella '777, further discloses that a similar semiconductor wafer substrate (either of chip 10 or circuit board 16), the semiconductor wafer substrate having at least one electrode (items 12 and 14) on a first surface thereof. Ciardella '777 discloses the discharging head (nozzle 70 and

Art Unit: 1734

subelements - see Figure 3), the resin container unit (syringe 84), the drive mechanism (conveyor 22 and XYZ electromechanical positioner 38), and control unit (items 18, 38, 40, and 42) for controlling the discharging head and the drive mechanism (see rejection of claim 1 and 23 above) and wherein the substrate is held in a substrate holding unit (conveyor and fixer - see lift and lock mechanism in column 3, lines 5-13 and column 5, lines 36-40). The camera and vision circuit is an image information device (item 16 and 44) that provides image information of the substrate (such as the location of the drops), and effectively allows for the positioning of the drive mechanism of the nozzle, and therefore provides and is capable of providing the control unit functionality as claim.

As to claim 35, Bouras as incorporated discloses that at least one electrode has a protruded shape (as seen in Figures 1 and 2).

As to claim 36, Bouras and Ciardella '777 is capable of being used to control said discharging head and said drive mechanism such that the first surface of the semiconductor wafer is covered by said raw sealant resin except a tip portion of said protruded-shaped electrode.

As to claim 38, Bouras, which is an improvement of Ciardella '777, discloses that the substrate holding unit is provided with a substrate temperature control mechanism (item 44, 46 and 47, see column 5, lines 32-47) for controlling a temperature of at least said semiconductor wafer substrate.

As to claim 40, both Bouras (item 26) and Ciardella '777 disclose a heater (see column 6, lines 64-67 and column 7, lines 1-19) for heating said raw sealant resin contained in said resin container unit.

***Claim Rejections - 35 USC § 103***

9. Claims 4, 26, 34-36, 38 and 40 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ciardella (US 5,711,989) as applied to claims 1, 2, 6-8, 10, 11 and 23, 24, 28-30, and 32-33 above, and further in view of Bouras (US 5,906,682).

As to claim 4 and 26, Ciardella does not suggest that the substrate holding unit is provided with a temperature control mechanism.

Bouras (see column 3, lines 62-65) discloses an improvement of Ciardella wherein the substrate holding unit is provided with a substrate temperature control mechanism (item 44, 46 and 47, see column 5, lines 32-47) for controlling a temperature of at least said semiconductor wafer substrate. One in the art would appreciate that preventing hot spots on the circuit board and its components would protect the substrate from damage. Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have utilize such a temperature control mechanism in order to protect the substrate from overheating.

As for claim 34, Ciardella discloses the discharging head (nozzle 70 and subelements - see Figure 3), the resin container unit (syringe 84), the drive mechanism (conveyor 22 and XYZ electromechanical positioner 38), and control unit (items 18, 38, 40, and 42) for controlling the discharging head and the drive mechanism (see rejection

Art Unit: 1734

of claim 1 and 23 above) and wherein the substrate is held in a substrate holding unit (conveyor and fixer - see lift and lock mechanism in column 3, lines 5-13 and column 5, lines 36-40). The camera and vision circuit is an image information device (item 16 and 44) that provides image information of the substrate (such as the location of the drops), and effectively allows for the positioning of the drive mechanism of the nozzle, and therefore provides and is capable of providing the control unit functionality as claim.

However, while Ciardella does disclose a semiconductor substrate (circuit board 35), Ciardella is silent as to the details of the circuit board.

Bouras, which discloses an improvement of Ciardella, further discloses that a similar semiconductor wafer substrate (either of chip 10 or circuit board 16), the semiconductor wafer substrate having at least one electrode (items 12 and 14) on a first surface thereof. Therefore, one in the art would appreciate that the claimed substrate can be used with Ciardella. One in the art would utilize the claimed substrate in order to properly coat the substrate and to reduce the need for multiple versions of similar apparatus. Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have utilized such a substrate with the apparatus of Ciardella in order to reduce apparatus costs.

As to claim 35, Bouras as incorporated discloses that at least one electrode has a protruded shape (as seen in Figures 1 and 2).

As to claim 36, Ciardella is capable of being used to control said discharging head and said drive mechanism such that the first surface of the semiconductor wafer is

Art Unit: 1734

covered by said raw sealant resin except a tip portion of said protruded-shaped electrode.

As to claim 38, Ciardella does not suggest that the substrate holding unit is provided with a temperature control mechanism.

Bouras discloses an improvement of Ciardella wherein the substrate holding unit is provided with a substrate temperature control mechanism (item 44, 46 and 47, see column 5, lines 32-47) for controlling a temperature of at least said semiconductor wafer substrate. One in the art would appreciate that preventing hot spots on the circuit board and its components would protect the substrate from damage. Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have utilize such a temperature control mechanism in order to protect the substrate from overheating.

As to claim 40, Ciardella discloses a heater (see column 6, lines 64-67 and column 7, lines 1-19) for heating said raw sealant resin contained in said resin container unit.

10. Claims 3, 5, 25, 27, 31 and 37 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ciardella as applied to claims 1 and 23 above, or Ciardella and Bouras as applied to claim 34 above, and further in view of Nakazawa (US 5,935,375).

As to claim 3, 25 and 37, Ciardella, Ciardella '777 and/or Bouras does not disclose that said discharging mechanism is provided with a plurality of discharging nozzles.

Nakazawa discloses using a discharging mechanism is provided with a plurality of discharging nozzles (see Figures 7A, 7B, 8A, and 8B). Nakazawa discloses that different nozzle sizes can be used in order minimize the differences in the rate of resin dispensing, so that the formation of resin-less voids is deterred (column 4, lines 26-45). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have utilized multiple nozzles as in Nakazawa in order to avoid resin-less voids.

Furthermore, as to claims 5, 25, and 37, the discharging nozzle of Nakazawa meet the limitation of being two different kinds of discharging mechanisms, heads or means.

As to claim 9 and 31, the control unit of Ciardella and/or Bouras is capable of said control unit controls said discharging mechanism and said drive mechanism such that a first discharging mechanism of said at least two kinds of discharging mechanisms is capable of discharging droplets of raw sealant resin of an amount smaller than other discharging mechanisms used for discharging said raw sealant resin for an area in a vicinity of said electrode.

11. Claims 5, 9, 27, 31 and 39 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ciardella as applied to claims 1 and 23 above, or Ciardella and

Bouras as applied to claim 34 above, or Bouras as evidenced by Ciardella '777, and further in view of Prentice (US 6,007,631).

As to claim 5, 27, and 39, Ciardella, Ciardella '777 and/or Bouras does not disclose at least two kinds of discharging mechanisms, heads or means, each being capable of discharging respective different amounts of raw sealant resin.

Prentice discloses at least two kinds of discharging mechanisms, heads or means, (see Figure 5) each being capable of discharging respective different amounts of raw sealant resin. Prentice discloses that such multiple mechanisms allow for parallel processing of the substrates (see abstract). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have two discharging mechanisms in order to achieve parallel processing.

As to claim 9 and 31, the control unit of either Ciardella and/or Bouras is capable of said control unit controls said discharging mechanism and said drive mechanism such that a first discharging mechanism of said at least two kinds of discharging mechanisms is capable of discharging droplets of raw sealant resin of an amount smaller than other discharging mechanisms used for discharging said raw sealant resin for an area in a vicinity of said electrode.

12. Claims 5, 9, 27, 31 and 39 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ciardella as applied to claims 1 and 23 above, or Ciardella and Bouras as applied to claim 34 above, or Bouras as evidenced by Ciardella '777, and further in view of Cavallaro (US 6,017,392).

As to claim 5, 27, and 29, Ciardella and/or Bouras does not disclose at least two kinds of discharging mechanisms, heads or means, each being capable of discharging respective different amounts of raw sealant resin.

Cavallaro discloses at least two kinds of discharging mechanisms, heads or means, each being capable of discharging respective different amounts of raw sealant resin. Cavallaro discloses that each mechanism can be connected to or include different types of nozzles and/or dispense different types of liquids (column 2).

Cavallaro discloses that this system allows for the assembly to dispense at different locations without it being necessary to move the entire pump assembly every time a dot is dispensed. Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have two discharging mechanisms in order to dispense at multiple locations without moving the entire assembly.

As to claim 9 and 31, the control unit of Ciardella and/or Bouras is capable of said control unit controls said discharging mechanism and said drive mechanism such that a first discharging mechanism of said at least two kinds of discharging mechanisms is capable of discharging droplets of raw sealant resin of an amount smaller than other discharging mechanisms used for discharging said raw sealant resin for an area in a vicinity of said electrode.

### ***Conclusion***

13. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP



Art Unit: 1734

§ 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).


A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to George R. Koch III whose telephone number is (571) 272-1230 (TDD only). If the applicant cannot make a direct TDD-to-TDD call, the applicant can communicate by calling the Federal Relay Service at 1-866-377-8642 and giving the operator the above TDD number. The examiner can normally be reached on M-Th 10-7.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Christopher Fiorilla can be reached on (571) 272-1187. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Art Unit: 1734

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



George R. Koch III  
Patent Examiner  
Art Unit 1734

GRK  
2/17/2007